

PRINCIPAL INVESTIGATORS

Name	Research Interests	Office	Tel	E-mail
A. I. Akinwande	Micro- and Nano- structures for sensors & actuators and vacuum microelectronics. Devices for large area electronics and flat panel displays.	39-553a	617-258-7974	akinwand@mtl.mit.edu
D. A. Antoniadis	Fabrication, measurements and modeling of silicon- and germanium-based devices for high-speed and low-power integrated circuits.	39-427b	617-253-4693	daa@mtl.mit.edu
M. A. Baldo	Molecular electronics, integration of biological materials and conventional electronics, electrical and exciton transport in organic materials, energy transfer, metal-organic contacts, nanomechanical transistors.	13-3053	617-452-5132	baldo@mit.edu
K. K. Berggren	Superconductive nanodevice physics and applications; nanofabrication methods, processes, and tool-development for application to quantum computing and single-photon detection.	36-219	617-324-0272	berggren@mit.edu
S. N. Bhatia	Micro- and nano-technologies for tissue repair and regeneration. Applications in liver tissue engineering, cell-based BioMEMS, and nanobiotechnology.	E19-502d	617-324-0221	sbhatia@mit.edu
D. S. Boning	Design for manufacturability (DFM) of processes, devices, and integrated circuits. Characterization and modeling of variation in semiconductor and MEMS manufacturing, with emphasis on chemical-mechanical polishing (CMP), electroplating, plasma etch, and embossing processes.	38-435	617-253-0931	boning@mtl.mit.edu
V. M. Bove, Jr.	Sensing, display, user interface, and computation for consumer electronics applications, particularly self-organizing ecosystems of devices. Advanced data representations for multimedia.	E15-368B	617-253-0334	vmb@media.mit.edu
V. Bulović	Physical properties of organic and organic/inorganic nanocrystal composite thin films and structures; development of nanostructured electronic and optoelectronic devices.	13-3138	617-253-7012	bulovic@mit.edu
A. P. Chandrakasan	Design of digital integrated circuits and systems. Energy efficient implementation of signal processing, communication and medical systems. Circuit design with emerging technologies.	38-107	617-258-7619	anantha@mtl.mit.edu
L. Daniel	Parameterized model order reduction of linear and nonlinear dynamical systems; mixed-signal, RF and mm-wave circuit simulation and modeling for optimization; parasitic extraction and accelerated integral equation solvers; simulation and modeling of the human cardiovascular circulatory system.	36-849	617-253-2631	luca@mit.edu
J. L. Dawson	Design of RF and mixed-signal CMOS ICs for communications systems and medical applications.	39-527A	617-253-5281	jldawson@mtl.mit.edu
J. A. del Alamo	Microelectronics device technologies for gigahertz and gigabit-per-second communication systems: physics, modeling, technology and design. InGaAs as a post-CMOS semiconductor logic technology. Technology and pedagogy of online laboratories for engineering education.	39-567a	617-253-4764	alamo@mit.edu
C. G. Fonstad, Jr.	Compound semiconductor heterostructure devices and physics. Optoelectronics: laser diodes, photodiodes, quantum effect devices, and OEICs. Monolithic heterogeneous integration. Microscale thermophotovoltaics.	13-3050	617-253-4634	fonstad@mit.edu
S. Gradečak	Nano-electronics and photonics; correlation of structural, optical, electronic, and magnetic properties of semiconducting materials; inorganic nanowires, nanowire heterostructure and devices; III-V semiconductor epitaxial films and low-dimensional systems; development of advanced electron microscopy techniques.	13-5094	617-253-9896	gradecak@mit.edu
J. Han	Nanofluidic / Microfluidic technologies for advanced biomolecule analysis and sample preparation: novel nanofluidic phenomena, nanofluidic biomolecule separation and pre-concentration, Molecular transport in nano-confined space.	36-841	617-253-2290	jjhan@mit.edu

Name	Research Interests	Office	Tel	E-mail
J. L. Hoyt	Fabrication and device physics of silicon-based heterostructures and nanostructures. High mobility Si and Ge-channel MOSFETs, nanowire FETs, novel transistor structures, and silicon-germanium photodetectors for electronic/photonic integrated circuits.	39-427A	617-452-2873	jlhoyt@mtl.mit.edu
Q. Hu	Physics and applications of millimeter-wave, terahertz, and infrared devices.	36-465	617-253-1573	qhu@mit.edu
P. Jarillo-Herrero	Quantum electronic transport in novel low-dimensional systems such as graphene and carbon nanotubes. Specific areas include: graphene nanoribbons, superconducting graphene nanoelectronic devices, suspended graphene devices, and graphene-carbon nanotube junctions.	13-2017	617-253-3653	pjarillo@mit.edu
S.-G. Kim	Nanomanufacturing, carbon nanotube assembly, piezoelectric energy harvesting, PZT MEMS, MEMS by ink jet printing	1-310	617-452-2472	sangkim@mit.edu
L. C. Kimerling	Electronic, photonic, and magnetic materials; nanotechnology	13-4118	617-253-5383	lckim@mit.edu
L. A. Kolodziejski	Research in integrated photonic devices and optoelectronic components. Design and fabrication of photonic crystals and III-V semiconductor devices. Semiconductor materials growth and characterization.	36-287	617-253-6868	leskolo@mit.edu
J. Kong	Synthesis, characterization and applications of carbon-based nanomaterials (nanotubes and graphene) and inorganic nanowires.	13-3065	617-324-4068	jingkong@mit.edu
J. H. Lang	Analysis, design and control of electromechanical systems with application to traditional electromagnetic actuators, micron-scale actuators and sensors (MEMS), and flexible structures.	10-176	617-253-4687	lang@mit.edu
H.-S. Lee	Analog and mixed-signal integrated circuits, with a particular emphasis in data conversion circuits in scaled CMOS.	39-521	617-253-5174	hslee@mtl.mit.edu
C. Livermore	MicroElectroMechanical Systems (MEMS). Design and fabrication of high power microsystems, including pumps and MEMS components for lasers. Energy storage in carbon nanotube springs. Assembly of MEMS devices. Self-assembly techniques for nano- and micro-scale manufacturing.	3-449C	617-253-6761	livermor@mit.edu
S. R. Manalis	Microdevices for biomolecular and single cell analysis.	E15-422	617-253-5039	scottm@media.mit.edu
I. Masaki	VLSI architecture. Emphasis on interrelationship among applications, systems, algorithms, and chip architectures. Major application fields include intelligent transportation systems, video, and multimedia.	38-107	617-253-8532	imasaki@aol.com
T. Palacios	Design, fabrication and characterization of novel electronic devices in wide bandgap semiconductors; polarization and bandgap engineering; transistors for sub-mm wave power and digital applications; new ideas for power conversion and generation; interaction of biological systems with semiconductor materials and devices; nanowires and graphene –based transistors.	39-567B	617-324-2395	tpalacios@mit.edu
D. J. Perreault	Power electronics and energy conversion, Electronic circuit design and control. Applications to industrial, commercial, scientific, transportation, and biomedical systems.	10-039	617-258-6038	djperrea@mit.edu
R. J. Ram	Photonic devices for applications in communications, computing, and biological sensing with special emphasis on fiber-to-the-home, InP photonic integration, Silicon photonics and high speed interconnects, microscale bioreactors, and biomanufacturing.	36-491	617-253-4182	rajeev@mit.edu
C. A. Ross	Fabrication, properties and applications of magnetic and magneto-optical films, nanostructures and devices; self assembly, block copolymer lithography.	13-4005	617-258-0223	caross@mit.edu
R. Sarpeshkar	Biomedical systems, circuit modeling of biology, bio-inspired systems.	38-294	617-258-6599	rahuls@mit.edu

Name	Research Interests	Office	Tel	E-mail
M. L. Schattenburg	Advanced lithography, including x-ray, electron-beam, ion-beam, and optical. Nanotechnology and nanofabrication. Precision engineering and nano-accuracy dimensional metrology. Advanced interference lithography technology for high-accuracy patterning of general grating and grid patterns. Micro and nanometer fabrication technology applied to advanced astronomical and laboratory instrumentation. Silicon micromachined structures applied to high-precision optical assembly. X-ray optics and instrumentation.	37-487	617-253-3180	marks@space.mit.edu
M. A. Schmidt	Micromechanical systems (MEMS). Microfabrication technologies for integrated circuits, sensors, and actuators; design of micromechanical sensor and actuator systems; mechanical properties of microelectronic materials with emphasis on silicon wafer bonding technology; integrated microsensors, and microfluidic devices. Novel applications of MEMS and nanotechnologies to a variety of fields, including miniature gas turbines, miniature chemical reactors, miniature gas analyzers, microswitches, biological applications, and sensors monolithically integrated with electronics.	39-521	617-253-7817	schmidt@mtl.mit.edu
H. I. Smith	Co-director, NanoStructures Lab. Development of nanofabrication tools and techniques aimed at reaching molecular dimensions and sub-1nm positional accuracy; nanophotonics; templated self assembly.	36-225	617-253-6865	hismith@mit.edu
C. G. Sodini	Electronics and integrated circuit design and technology. More specifically, technology intensive integrated circuit and systems design, with application toward sensory interface electronics and wireless communication emphasizing analog signal processing and RF integrated circuits.	39-527B	617-253-4938	sodini@mtl.mit.edu
V. Stojanović	On-chip interconnects and high-speed off-chip interfaces (electrical, photonic). Circuit and interconnect design with novel devices (CNTs, NEM relays, Si-photonic). Modeling and analysis of noise and dynamics in circuits and systems. Application of optimization techniques to digital communications, analog and digital circuits. Digital communications and signal-processing architectures, clock generation and distribution, high-speed digital circuit design, VLSI and mixed-signal IC design.	38-260	617-324-4913	vlada@mit.edu
C. V. Thompson	Processing and property optimization for thin films and nanostructures for applications in electronic and electromechanical integrated device systems. Advanced, reliable integrated circuit interconnects.	13-5069	617-253-7652	cthomp@mit.edu
H. L. Tuller	Energy related materials, micro-fuel cells, solar cells, resonant and chemoresistive sensors, high K dielectrics, electro-optic and piezoelectric thin films, solid state ionics, thin film transistors, MEMS structures and devices.	13-3126	617-253-6890	tuller@mit.edu
J. Voldman	Microtechnology for basic and applied cell biology; Microsystems for stem cell biology; Electrostatics at the microscale, especially dielectrophoresis.	36-824	617-253-2094	voldman@mit.edu
E. N. Wang	Micro/nanoscale transport micro-/nanoscale transport phenomena, MEMS/NEMS design and sensing, optical diagnostics, numerical modeling, and surface nanoengineering for thermal management, energy conversion, and water desalination.	3-461B	617-324-3311	enwang@mit.edu
B. L. Wardle	Nano-engineered composites; nanocomposites; MEMS Power Devices and Energy Harvesting; Advanced Composite Materials and Systems; Structural Health Monitoring (SHM); Fracture, Fatigue and Damage Mechanics; Durability Modeling/Testing; Finite-Element Modeling; Structural Response and Testing; Buckling Mechanics	33-314	617-252-1539	wardle@mit.edu